PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3963126

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WEI-YU CHEN	07/05/2016
LI-HSIEN HUANG	07/05/2016
AN-JHIH SU	07/05/2016
HSIEN-WEI CHEN	07/05/2016

RECEIVING PARTY DATA

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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15208764

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NAME OF SUBMITTER:	TUYEN LY
SIGNATURE:	/tuyen ly/
DATE SIGNED:	07/13/2016

Total Attachments: 2
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ASSIGNMENT

WHEREAS, Wei-Yu CHEN, Li-Hsien HUANG, An-Jhih SU, and Hsien-Wei CHEN hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **CHIP PACKAGE STRUCTURE WITH MOLDING LAYER AND METHOD FOR FORMING THE SAME**

Filed: 07/13/2016 Serial No. 15/208,764

Executed on: 07/05/2016

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., of No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C., hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

2016. 07. 05
Date

Wei-Yu Chen
Name: Wei-Yu CHEN (Last name: CHEN)

2016. 7. 5
Date

Li-Hsien Huang
Name: Li-Hsien HUANG (Last name: HUANG)

2016. 7. 05
Date

An-Jhih Su
Name: An-Jhih SU (Last name: SU)

2016. 7. 5
Date

Hsien-Wei Chen
Name: Hsien-Wei CHEN (Last name: CHEN)